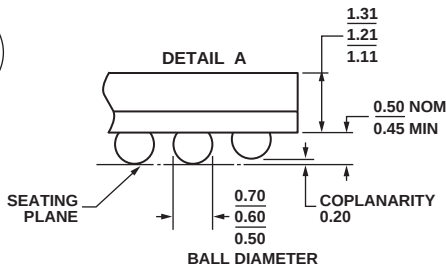
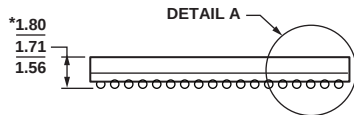
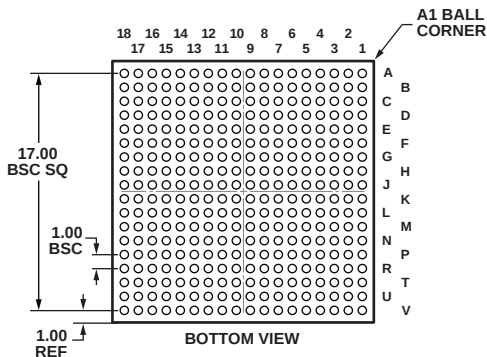
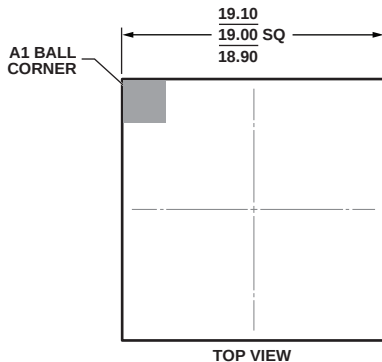


324-Ball Chip Scale Package Ball Grid Array [CSP_BGA] (BC-324-1)

Dimensions shown in millimeters



*COMPLIANT TO JEDEC STANDARDS MO-192-AAG-1 WITH
THE EXCEPTION TO PACKAGE HEIGHT.